



OPA137 OPA2137 OPA4137

LOW COST FET-INPUT OPERATIONAL AMPLIFIERS *MicroAmplifier*™ Series

FEATURES

- FET INPUT: I_B = 5pA
- LOW OFFSET VOLTAGE: 1.5mV
- WIDE SUPPLY RANGE: ±2.25V to ±18V
- LOW QUIESCENT CURRENT: 220µA/channel
- EXCELLENT SPEED/POWER: 1MHz
- INPUT TO POSITIVE SUPPLY
- MicroSIZE PACKAGES: SOT-23-5, MSOP-8
- SINGLE, DUAL, AND QUAD

APPLICATIONS

- STRAIN GAGE AMPLIFIER
- PHOTODETECTOR AMPLIFIER
- PRECISION INTEGRATOR
- BATTERY-POWERED INSTRUMENTS

OPA137

- TEST EQUIPMENT
- ACTIVE FILTERS

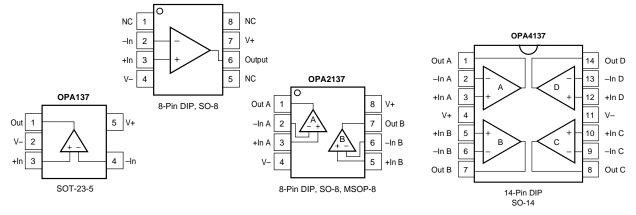
DESCRIPTION

OPA137 series FET-input operational amplifiers are designed for low cost and miniature applications. In addition to small size (SOT-23-5 and MSOP-8 packages), they provide low input bias current (5pA), low quiescent current ($220\mu A$ / channel), and high open-loop gain (94dB).

Either single (+4.5V to +36V) or dual (± 2.25 to $\pm 18V$) supplies can be used. The input common-mode voltage range includes the positive supply—suitable for many single-supply applications. Single, dual, and quad versions have identical specifications for maximum design flexibility.

OPA137 op amps are easy to use and free from phase inversion and overload problems found in some FET-input amplifiers. High performance, including linearity, is maintained as the amplifiers swing to their specified limits. In addition, the combination of high slew rate $(3.5V/\mu s)$ and wide bandwidth (1MHz) provide fast settling time assuring good dynamic response. Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

The single (OPA137) packages are the tiny 5-lead SOT-23-5 surface mount, SO-8 surface mount, and 8-pin DIP. The dual (OPA2137) comes in the miniature MSOP-8 surface mount, SO-8 surface mount, and 8-pin DIP packages. The quad (OPA4137) packages are the SO-14 surface mount and the 14-pin DIP. All are specified from -40° C to $+85^{\circ}$ C and operate from -55° C to $+125^{\circ}$ C. A SPICE macromodel is available for design analysis.



International Airport Industrial Park • Mailing Address: PO Box 11400, Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd., Tucson, AZ 85706 • Tel: (520) 746-1111 • Twx: 910-952-1111 Internet: http://www.burr-brown.com/ • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS: V_S = $\pm 15V$

At T_A = +25°C, R_L = 10k Ω connected to ground, unless otherwise noted. **Boldface** limits apply over the specified temperature range, T_A = -40°C to +85°C.

		OP	A137N, U A2137E, U PA4137U,	Ĵ, Р	OPA	137NA, U 2137EA, L A4137UA	JA, PA	
PARAMETER	CONDITION	MIN	ТҮР	MAX	MIN	ТҮР	MAX	UNITS
	RR $V_{\rm S} = \pm 3V$ to $\pm 18V$ dc		± 1.5 ± 2.5 ± 15 ± 90 0.6	±3 ±7 ±250 ±250		±2.5 ±3.5 * *	±10 ± 15 * *	mV mV μV/°C μV/V μV/V μV/V
INPUT BIAS CURRENT Input Bias Current vs Temperature Input Offset Current	I _B I _{OS}	See	±5 Typical C ±2	±100 Curve ±50		* * *	*	рА pA
NOISE Input Voltage Noise, f = 0.1 to 10Hz Input Voltage Noise Density, f = 1kHz Current Noise Density, f = 1kHz	e _n i _n		2 45 1.2			* * *		μVp-p nV/√Hz fA/√Hz
INPUT VOLTAGE RANGE Common-Mode Voltage Range M Common-Mode Rejection Ratio CM OPA137, OPA2137 CM OPA4137 T T _A = -40°C to +85°C OPA4137 OPA137, OPA2137 OPA4137	V _{CM} RR $V_{CM} = -12V$ to 15V $V_{CM} = -12V$ to 15V	(V-) + 3 76 74 72 70	84 84	(∨+)	* 70 70 70 70	* *	*	V dB dB dB dB
INPUT IMPEDANCE Differential Common-Mode			10 ¹⁰ 1 10 ¹² 2			*		Ω pF Ω pF
OPEN-LOOP GAINOpen-Loop Voltage Gain $T_A = -40^{\circ}C$ to $+85^{\circ}C$	A_{OL} $V_{O} = -13.8V$ to 13.9V $V_{O} = -13.8V$ to 13.9V	86 86	94		*	*		dB dB
	$\begin{array}{c} \text{G} = 1 \\ \text{G} = 1, \ 10V \ \text{Step}, \ \text{C}_{\text{L}} = 100 \text{pF} \\ \text{G} = 1, \ 10V \ \text{Step}, \ \text{C}_{\text{L}} = 100 \text{pF} \\ \text{V}_{\text{IN}} \bullet \text{G} = \text{V}_{\text{S}} \\ \text{+N} \text{G} = 1, \ \text{f} = 1 \text{kHz}, \ 3.5 \text{Vrms} \end{array}$		1 3.5 8 10 1 0.05			* * * * *		MHz V/μs μs μs %
$T_A = -40^{\circ}C$ to $+85^{\circ}C$	DUT Isc DAD	(V−) + 1.2 (V−) + 1.2	-25/+60 1000	(V+) – 1.1 (V+) – 1.1	*	* *	* *	V V mA pF
POWER SUPPLYSpecified Operating RangeOperating Voltage RangeDual SuppliesSingle SupplyQuiescent Current $T_A = -40^{\circ}C$ to $+85^{\circ}C$	V_S I_Q $I_O = 0$ $I_O = 0$	±2.25 ⁽¹⁾ +4.5	±15 ±220	±18 +36 ±270 ± 375	*	*	* * *	ν ν μΑ μΑ
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance SOT-23-5 Surface Mount MSOP-8 Surface Mount SO-8 Surface Mount 8-Pin DIP SO-14 Surface Mount 14-Pin DIP	θ _{JA}	-40 -55 -55	200 150 150 100 100 80	+85 +125 +125	* *	* * * * *	* * *	°C °C °C °C °C °C °C °C °C °C °C °C °C °

 \ast Specifications the same as OPA137N, U, P.

NOTE: (1) At minimum power supply voltage inputs must be biased above ground in accordance with common-mode voltage range restrictions—see "Operating Voltage" discussion.



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

L	Supply Voltage, V+ to V	
L	Input Voltage	
L	Input Current	
L	Output Short-Circuit ⁽²⁾	Continuous
L	Operating Temperature	–55°C to +125°C
L	Storage Temperature	–55°C to +125°C
	Junction Temperature	+150°C
L	Lead Temperature (soldering, 10s)	300°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum ratings for extended periods may affact device reliability. (2) Short circuit to ground, one amplifier per package.



This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

SPECIFIED PACKAGE DRAWING TEMPERATURE PACKAGE ORDERING TRANSPORT RANGE PRODUCT PACKAGE NUMBER⁽¹⁾ MARKING NUMBER⁽²⁾ MEDIA Sinale OPA137N 5-Lead SOT-23-5 Surface Mount 331 -40°C to +85°C E37⁽³⁾ OPA137N/250 Tape and Reel OPA137N/3K Tape and Reel OPA137NA 5-Lead SOT-23-5 Surface Mount 331 -40°C to +85°C E37⁽³⁾ OPA137NA/250 Tape and Reel OPA137NA/3K Tape and Reel OPA137U Rails OPA137U SO-8 Surface Mount 182 -40°C to +85°C OPA137U OPA137U/2K5 Tape and Reel OPA137UA SO-8 Surface Mount 182 -40°C to +85°C OPA137UA OPA137UA Rails OPA137UA/2K5 Tape and Reel OPA137P 8-Pin DIP 006 -40°C to +85°C OPA137P OPA137P Rails OPA137PA 8-Pin DIP -40°C to +85°C OPA137PA OPA137PA 006 Rails Dual OPA2137E/250 OPA2137E MSOP-8 Surface Mount –40°C to +85°C E37⁽³⁾ Tape and Reel 337 OPA2137E/2K5 Tape and Reel OPA2137EA MSOP-8 Surface Mount 337 -40°C to +85°C E37⁽³⁾ OPA2137EA/250 Tape and Reel OPA2137EA/2K5 Tape and Reel OPA2137U SO-8 Surface Mount 182 -40°C to +85°C OPA2137U OPA2137U Rails Tape and Reel OPA2137U/2K5 OPA2137UA SO-8 Surface Mount 182 -40°C to +85°C OPA2137UA OPA2137UA Rails OPA2137UA/2K5 Tape and Reel **OPA2137P** 8-Pin DIP 006 -40°C to +85°C **OPA2137P OPA2137P** Rails **OPA2137PA** 8-Pin DIP 006 -40°C to +85°C OPA2137PA **OPA2137PA** Rails Quad OPA4137U –40°C to +85°C OPA4137U OPA4137U Rails SO-14 Surface Mount 235 Tape and Reel OPA4137U/2K5 OPA4137UA SO-14 Surface Mount 235 -40°C to +85°C OPA4137UA OPA4137UA Rails OPA4137UA/2K5 Tape and Reel OPA4137P 14-Pin DIP 010 -40°C to +85°C **OPA4137P** OPA4137P Rails **OPA4137PA** 14-Pin DIP 010 -40°C to +85°C **OPA4137PA OPA4137PA** Rails

PACKAGE/ORDERING INFORMATION

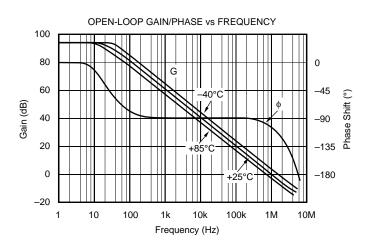
NOTES: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book. (2) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 3000 pieces of "OPA137NA/3K" will get a single 3000-piece Tape and Reel. For detailed Tape and Reel mechanical information, refer to Appendix B of Burr-Brown IC Data Book. (3) Grade information is marked on the reel.

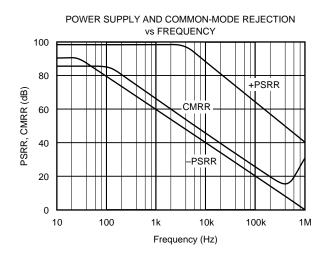
The information provided herein is believed to be reliable; however, BURR-BROWN assumes no responsibility for inaccuracies or omissions. BURR-BROWN assumes no responsibility for the use of this information, and all use of such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patent rights or licenses to any of the circuits described herein are implied or granted to any third party. BURR-BROWN does not authorize or warrant any BURR-BROWN product for use in life support devices and/or systems.

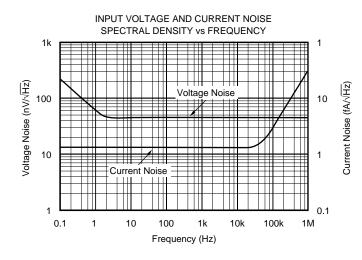


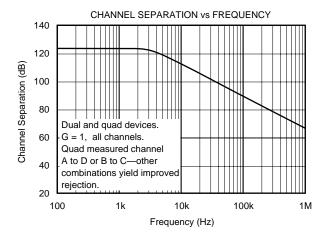
TYPICAL PERFORMANCE CURVES

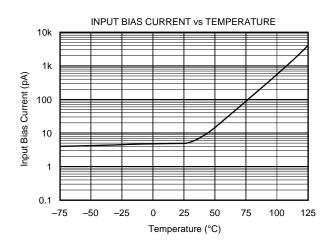
At T_A = +25°C, V_S = \pm 15V, R_L = 10k Ω , connected to ground, unless otherwise noted.



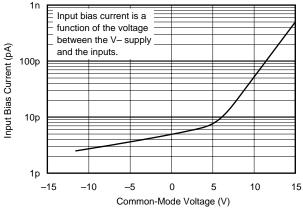








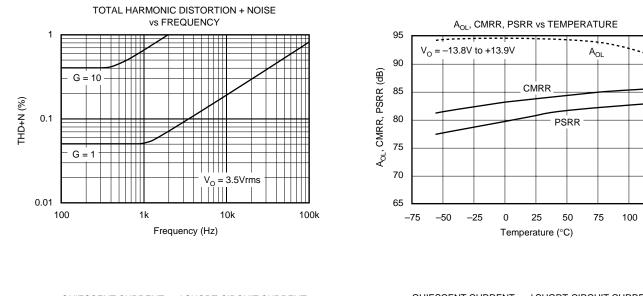
INPUT BIAS CURRENT vs INPUT COMMON-MODE VOLTAGE

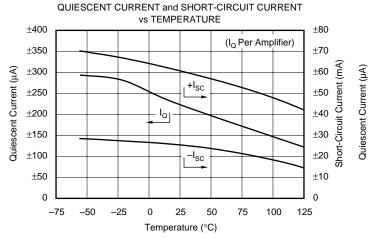


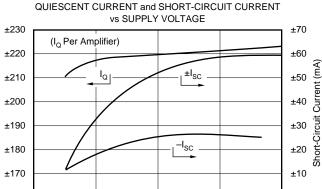


TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, V_S = \pm 15V, R_L = 10k Ω , connected to ground, unless otherwise noted.



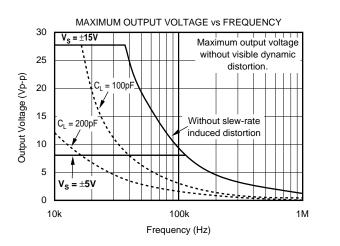


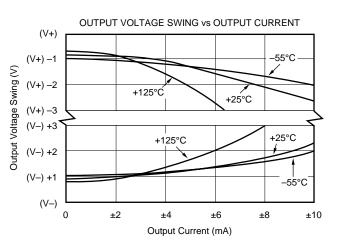


±10

Supply Voltage (V)

±15





125

0

±20

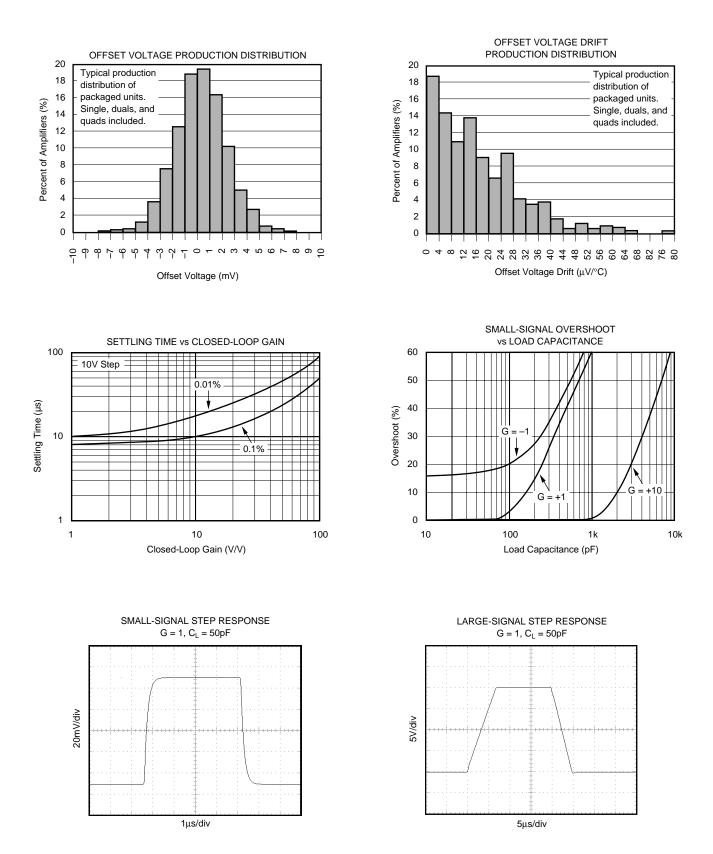
±160

0

±5

TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, V_S = ±15V, R_L = 10kΩ, connected to ground, unless otherwise noted.



OPA137, 2137, 4137

APPLICATIONS INFORMATION

OPA137 series op amps are unity-gain stable and suitable for a wide range of general-purpose applications. Power supply pins should be bypassed with 10nF ceramic capacitors or larger. All circuitry is completely independent in dual and quad versions, assuring normal performance when one amplifier in a package is overdriven or short circuited. Many key parameters are guaranteed over the specified temperature range, -40° C to $+85^{\circ}$ C.

OPERATING VOLTAGE

OPA137 op amps can be operated on power supplies as low as ± 2.25 V. Performance remains excellent with power supplies ranging from ± 2.25 V to ± 18 V (+4.5V to +36V single supply). Most parameters vary only slightly throughout this supply voltage range. Quiescent current and short-circuit current vs supply voltage are shown in Typical Performance Curves.

Operation at very low supply voltage ($V_S \le \pm 3V$) requires careful attention to ensure that the common-mode voltage remains within the linear range, $V_{CM} = (V-)+3V$ to (V+). Inputs may need to be biased above ground in accordance with the common-mode voltage range restrictions for linear operation.

INPUT VOLTAGE

The input common-mode voltage range of OPA137 series op amps extends from (V-)+3V to the positive rail, V+. For normal operation, inputs should be limited to this range. The inputs may go beyond the power supplies without output phase-reversal. Many FET-input op amps (such as TL061 types) exhibit phase-reversal of the output when the input common-mode range is exceeded. This can occur in voltagefollower circuits, causing serious problems in control loop applications.

Input terminals are diode-clamped to the power supply rails for ESD protection. If the input voltage can exceed the negative supply by 500mV, input current should be limited to 2mA (or less). If the input current is not adequately limited, you may see unpredicatable behavior in the other amplifiers in the package. This is easily accomplished with an input resistor as shown in Figure 1. Many input signals are inherently current-limited, therefore, a limiting resistor may not be required.

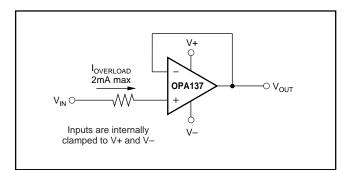


FIGURE 1. Input Current Protection for Voltages Exceeding the Supply Voltage.

HIGH-SIDE CURRENT SENSING

Many applications require the sensing of signals near the positive supply. The common-mode input range of OPA137 op amps includes the positive rail, enabling them to be used to sense power supply currents as shown in Figure 2.

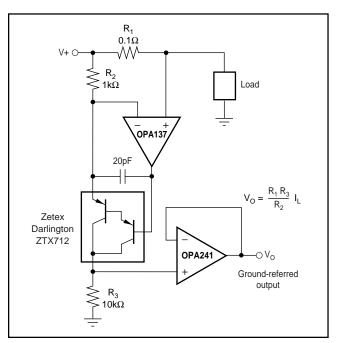


FIGURE 2. High-Side Current Monitor.

INPUT BIAS CURRENT

The input bias current is approximately 5pA at room temperature and increases with temperature as shown in the typical performance curve "Input Bias Current vs Temperature."

Input Bias current also varies with common-mode voltage and power supply voltage. This variation is dependent on the voltage between the negative power supply and the common-mode input voltage. The effect is shown in the typical performance curve "Input Bias Current vs Common-Mode Voltage."

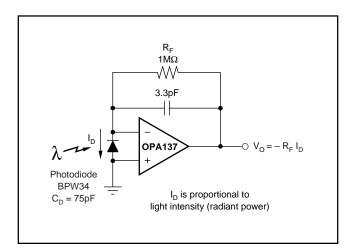


FIGURE 3. Photodetector Amplifier.

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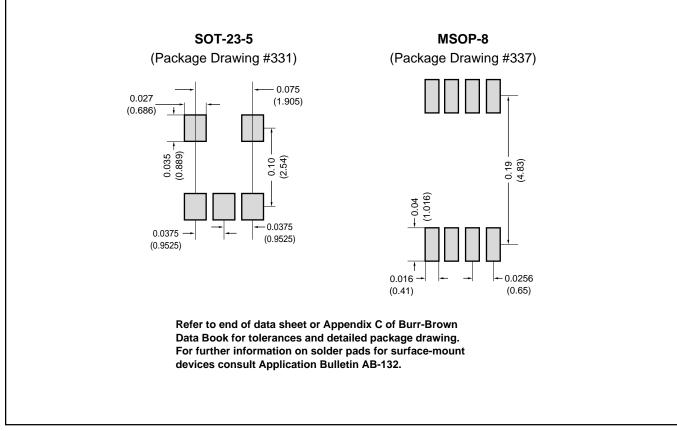


FIGURE 4. Recommended SOT-23-5 and MSOP-8 Solder Footprints.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
OPA137N/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	E37	Samples
OPA137N/250E4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	E37	Samples
OPA137N/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	E37	Samples
OPA137N/3KE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	E37	Samples
OPA137NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	E37	Samples
OPA137NA/250E4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	E37	Samples
OPA137NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	E37	Samples
OPA137P	LIFEBUY	PDIP	Ρ	8	50	Green (RoHS & no Sb/Br)	CU SNPB	N / A for Pkg Type		OPA137P	
OPA137PA	LIFEBUY	PDIP	Ρ	8	50	Green (RoHS & no Sb/Br)	CU SNPB	N / A for Pkg Type		OPA137P A	
OPA137U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 137U	Samples
OPA137UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 137U A	Samples
OPA137UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 137U A	Samples
OPA137UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 137U A	Samples
OPA137UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 137U A	Samples
OPA137UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 137U	Samples



PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samp
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
OPA2137E/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR	-40 to 85	E37	Samp
OPA2137E/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	E37	Samp
OPA2137E/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR	-40 to 85	E37	Samp
OPA2137E/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	E37	Samp
OPA2137EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR		E37	Samp
OPA2137EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		E37	Samj
OPA2137EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR		E37	Samj
OPA2137P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P	Sam
OPA2137PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P A	Sam
OPA2137PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P A	Samj
OPA2137PG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P	Sam
OPA2137U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 2137U	Sam
OPA2137U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 2137U	Sam
OPA2137UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 2137U A	Sam
OPA2137UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 2137U A	Sam
OPA2137UA/2K5E4	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI	-40 to 85		
OPA2137UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 2137U A	Sam



PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
OPA2137UE4	(1) ACTIVE	SOIC	D	8	75	(2) Green (RoHS & no Sb/Br)	(6) CU NIPDAU	(3) Level-3-260C-168 HR		(4/5) OPA 2137U	Samples
OPA4137P	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA4137P	Samples
OPA4137PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA4137P A	Samples
OPA4137PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA4137P A	Samples
OPA4137U	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U	Samples
OPA4137U/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U	Samples
OPA4137UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples
OPA4137UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples
OPA4137UAE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples
OPA4137UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



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⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



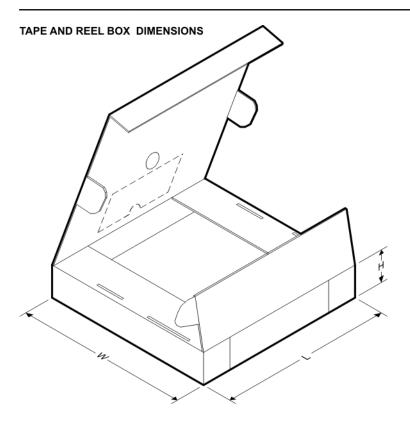
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA137N/250	SOT-23	DBV	5	250	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA137N/3K	SOT-23	DBV	5	3000	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA137NA/250	SOT-23	DBV	5	250	178.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
OPA137NA/3K	SOT-23	DBV	5	3000	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA137UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2137E/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137E/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2137UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4137U/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
OPA4137UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA137N/250	SOT-23	DBV	5	250	565.0	140.0	75.0
OPA137N/3K	SOT-23	DBV	5	3000	565.0	140.0	75.0
OPA137NA/250	SOT-23	DBV	5	250	565.0	140.0	75.0
OPA137NA/3K	SOT-23	DBV	5	3000	565.0	140.0	75.0
OPA137UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2137E/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2137E/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2137EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2137EA/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2137U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2137UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA4137U/2K5	SOIC	D	14	2500	367.0	367.0	38.0
OPA4137UA/2K5	SOIC	D	14	2500	367.0	367.0	38.0

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